

Features :

- * 1,048,576 words by 16 bits organization.
- * Fast access time and cycle time.
- * Dual $\overline{\text{CAS}}$ Input.
- * Low power dissipation.
- * Read-Modify-Write, $\overline{\text{RAS}}$ -Only Refresh, $\overline{\text{CAS}}$ -Before- $\overline{\text{RAS}}$ Refresh, Hidden Refresh and Test Mode Capability.
- * 1024 refresh cycles per 16ms.
- * Available in 400 mil SOJ / TSOPII Packages.
- * Single 3.3V \pm 0.3V Power Supply.
- * All inputs and Outputs are TTL compatible.
- * Extended Data-Out(EDO) Page Mode operation.
- * Self – refresh capability. (S-Version).

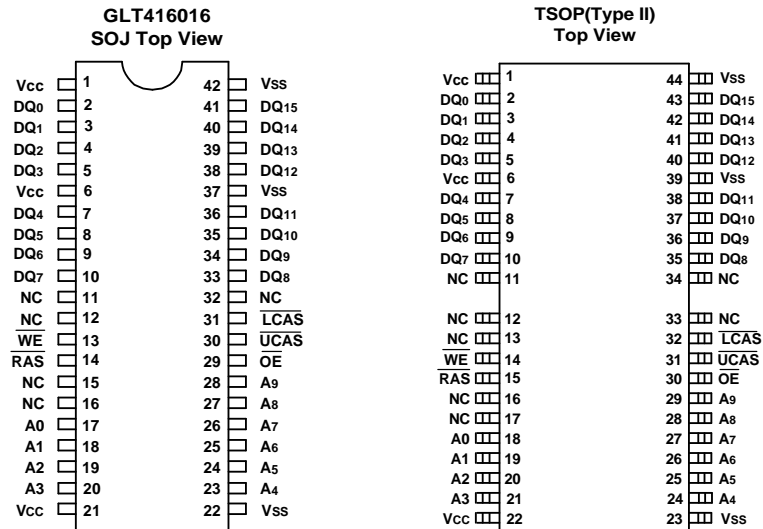
Description :

The GLT4160L16 is a 1,048,576 x 16 bit high-performance CMOS dynamic random access memory. The GLT4160L16 offers Fast Page mode with Extended Data Output, and has both BYTE WRITE and WORD WRITE access cycles via two $\overline{\text{CAS}}$ pins. The GLT4160L16 has symmetric address and accepts 1024-cycle refresh in 16ms interval.

All inputs are TTL compatible. EDO Page Mode operation allows random access up to 1024 x 16 bits within a page, with cycle times as short as 13ns.

The GLT4160L16 is best suited for graphics, and DSP applications requiring high performance memories.

HIGH PERFORMANCE	35	40	50	60
Max. $\overline{\text{RAS}}$ Access Time, (t_{RAC})	35 ns	40 ns	50 ns	60 ns
Max. Column Address Access Time, (t_{CAA})	18 ns	20 ns	25 ns	30 ns
Min. Extended Data Out Page Mode Cycle Time, (t_{PC})	13 ns	15 ns	20 ns	25 ns
Min. Read/Write Cycle Time, (t_{RC})	65 ns	70 ns	85 ns	104 ns
Max. $\overline{\text{CAS}}$ Access Time (t_{CAC})	11 ns	12 ns	14 ns	15 ns

Pin Configuration :

Pin Descriptions:

Name	Function
A ₀ - A ₉	Address Inputs
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{UCAS}}$	Column Address Strobe/Upper Byte Control
$\overline{\text{LCAS}}$	Column Address Strobe/Lower Byte Control
$\overline{\text{WE}}$	Write Enable
$\overline{\text{OE}}$	Output Enable
DQ ₀ - DQ ₁₅	Data Inputs / Outputs
V _{CC}	+3.3V Power Supply
V _{SS}	Ground
NC	No Connection

Absolute Maximum Ratings*

Operating Temperature, T_A (ambient)
0°C to +70°C
 Storage Temperature(plastic).....-55°C to +150°C
 Voltage Relative to V_{SS}.....-1.0V to + 4.6V
 Short Circuit Output Current.....50mA
 Power Dissipation.....1.0W

*Note: Operation above Absolute Maximum Ratings can adversely affect device reliability.

Capacitance*

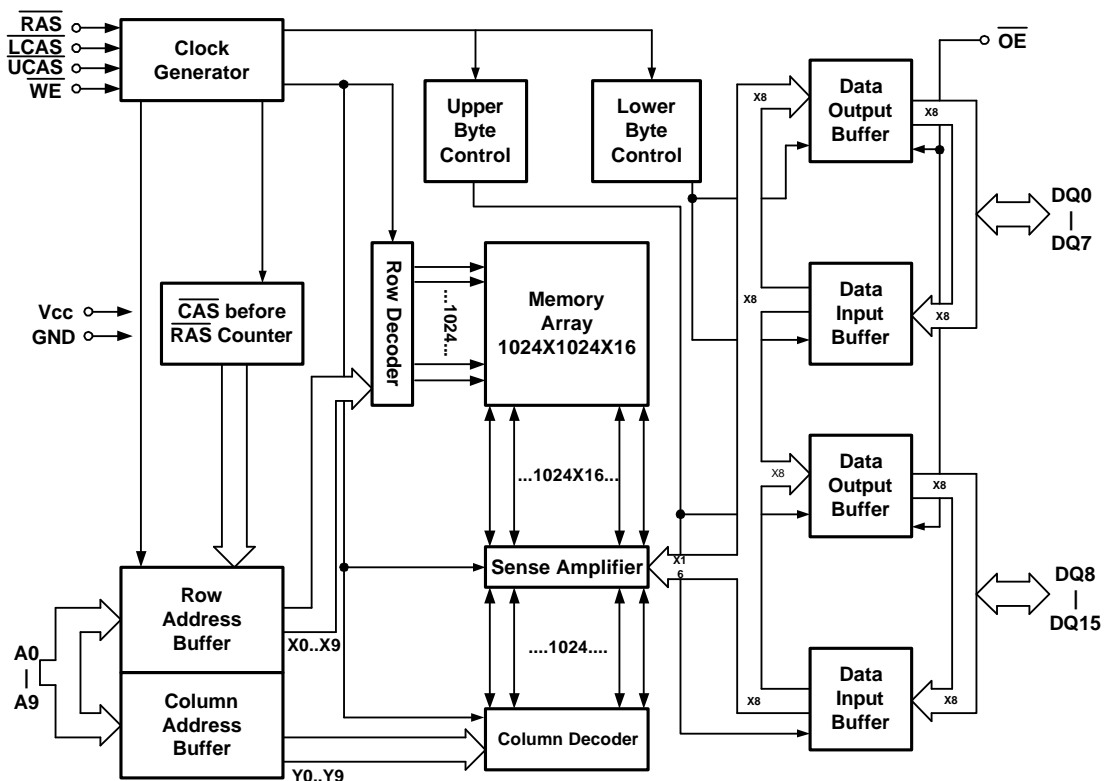
T_A=25°C, V_{CC}=3.3V±0.3V, V_{SS}=0V

Symbol	Parameter	Max.	Unit
C _{IN1}	Address Input	5	pF
C _{IN2}	$\overline{\text{RAS}}$, $\overline{\text{LCAS}}$, $\overline{\text{UCAS}}$, $\overline{\text{WE}}$, $\overline{\text{OE}}$	7	pF
C _{OUT}	Data Input/Output	7	pF

*Note: Capacitance is sampled and not 100% tested

Electrical Specifications

- $\overline{\text{CAS}}$ means $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
- All voltages are referenced to GND.
- After power up, wait more than 100µs and then, execute eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ or $\overline{\text{RAS}}$ -only refresh cycles as dummy cycles to initialize internal circuit.

Block Diagram :

DC and Operating Characteristics (1-2)

$T_A = 0^\circ\text{C to } 70^\circ\text{C}, V_{CC}=3.3\text{V}\pm 0.3\text{V}, V_{SS}=0\text{V},$ unless otherwise specified.

Sym.	Parameter	Test Conditions	Access Time	Min.	Typ	Max.	Unit	Notes
I _{LI}	Input Leakage Current (any input pin)	$0\text{V} \leq V_{IN} \leq V_{CC}+0.3\text{V}$ (All other pins not under test=0V)		-5		+5	μA	
I _{LO}	Output Leakage Current (for High-Z State)	$0\text{V} \leq V_{out} \leq V_{CC}$ Output is disabled (Hiz)		-5		+5	μA	
I _{CC1}	Operating Current, Random READ/WRITE	$t_{RC} = t_{RC}(\text{min.})$	$t_{RAC} = 35\text{ns}$ $t_{RAC} = 40\text{ns}$ $t_{RAC} = 50\text{ns}$ $t_{RAC} = 60\text{ns}$			170 160 150 140	mA	1,2
I _{CC2}	Standby Current,(TTL)	$\overline{\text{RAS}}, \overline{\text{UCAS}}, \overline{\text{LCAS}}$ at V_{IH} other inputs $\geq V_{SS}$				1	mA	
I _{CC3}	Refresh Current, RAS-Only	$\overline{\text{RAS}}$ cycling, $\overline{\text{UCAS}}, \overline{\text{LCAS}}$ at V_{IH} $t_{RC} = t_{RC}(\text{min.})$	$t_{RAC} = 35\text{ns}$ $t_{RAC} = 40\text{ns}$ $t_{RAC} = 50\text{ns}$ $t_{RAC} = 60\text{ns}$			170 160 150 140	mA	2
I _{CC4}	Operating Current, EDO Page Mode	$\overline{\text{RAS}}$ at V_{IL} , $\overline{\text{UCAS}}, \overline{\text{LCAS}}$ address cycling: $t_{PC}=t_{PC}(\text{min.})$	$t_{RAC} = 35\text{ns}$ $t_{RAC} = 40\text{ns}$ $t_{RAC} = 50\text{ns}$ $t_{RAC} = 60\text{ns}$			170 160 150 140	mA	1,2
I _{CC5}	Refresh Current, CAS Before RAS	$\overline{\text{RAS}}, \overline{\text{UCAS}}, \overline{\text{LCAS}}$ address cycling: $t_{RC}=t_{RC}(\text{min.})$	$t_{RAC} = 35\text{ns}$ $t_{RAC} = 40\text{ns}$ $t_{RAC} = 50\text{ns}$ $t_{RAC} = 60\text{ns}$			170 160 150 140	mA	1
I _{CC6}	Standby Current, (CMOS)	$\overline{\text{RAS}} \geq V_{CC}-0.2\text{V},$ $\overline{\text{UCAS}} \geq V_{CC}-0.2\text{V},$ $\overline{\text{LCAS}} \geq V_{CC}-0.2\text{V},$ All other inputs V_{SS}				0.5	mA	1
						200	μA	1,5
I _{CC7}	Self Refresh Current	$\overline{\text{RAS}} = \overline{\text{UCAS}} = \overline{\text{LCAS}} = V_{IL}$ $\overline{\text{WE}} = \overline{\text{OE}} = A_0 \sim A_9 = V_{CC}-0.2\text{V}$ or 0.2V $DQ_0 \sim DQ_{15} = V_{CC}-0.2\text{V}, 0.2\text{V}$ or Open				200	μA	
V _{IL}	Input Low Voltage			-0.3		+0.8	V	3
V _{IH}	Input High Voltage			2.0		$V_{CC}+0.3$	V	3
V _{OL}	Output Low Voltage	I _{OL} = 2mA				0.4	V	
V _{OH}	Output High Voltage	I _{OH} = -2mA		2.4			V	

Notes:

- I_{CC} is dependent on output loading when the device output is selected. Specified I_{CC}(max.) is measured with the output open.
- I_{CC} is dependent upon the number of address transitions specified I_{CC}(max.) is measured with a maximum of one transition per address cycle in random Read/Write and EDO Fast Page Mode.
- Specified V_{IL}(min.) is steady state operation. During transitions V_{IL}(min.) may undershoot to -1.0V for a period not to exceed 15ns. All AC parameters are measured with V_{IL}(min.) $\geq V_{SS}$ and V_{IH}(max.) $\leq V_{CC}$.
- Specified V_{IH}(max.) is steady state operation. During transitions V_{IH}(max.) may undershoot to +1.0V for a period not to exceed 15ns. All AC parameters are measured with V_{IL}(min.) $\geq V_{SS}$ and V_{IH}(max.) $\leq V_{CC}$.
- S-Version.

AC Characteristics

 $T_A = 0^\circ\text{C to } 70^\circ\text{C}$, $V_{CC} = 3V \pm 0.3V$, $V_{IH} / V_{IL} = 3.0/0 V$, $V_{OH}/V_{OL} = 2.0/0.8V$

 An initial pause of 100 μs and 8 $\overline{\text{CAS}}$ -before-RAS or RAS-only refresh cycles are required after power-up.

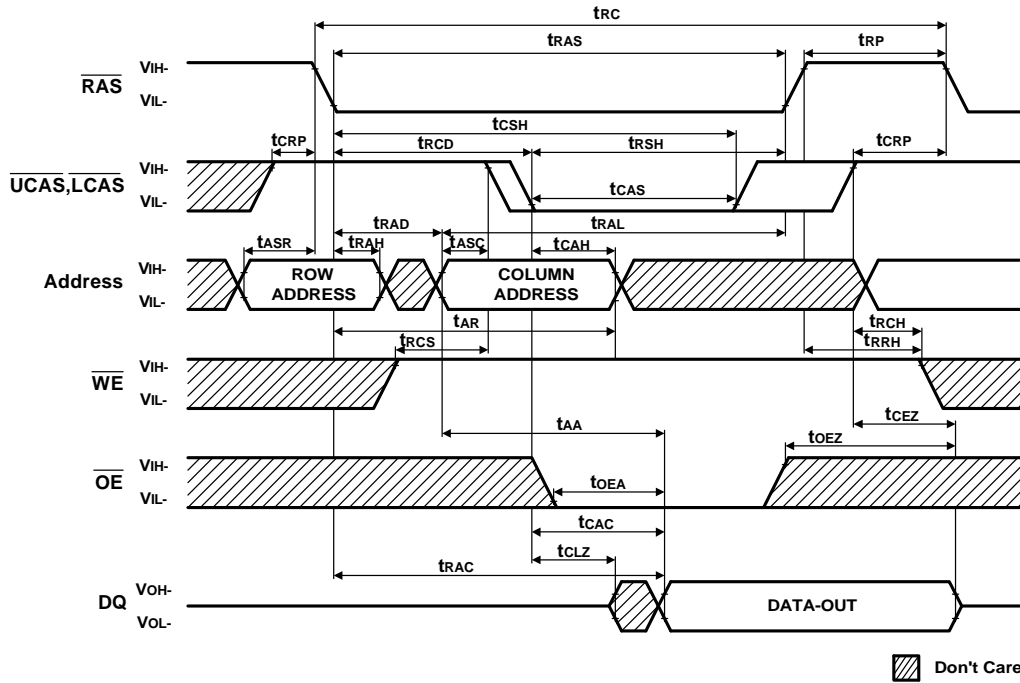
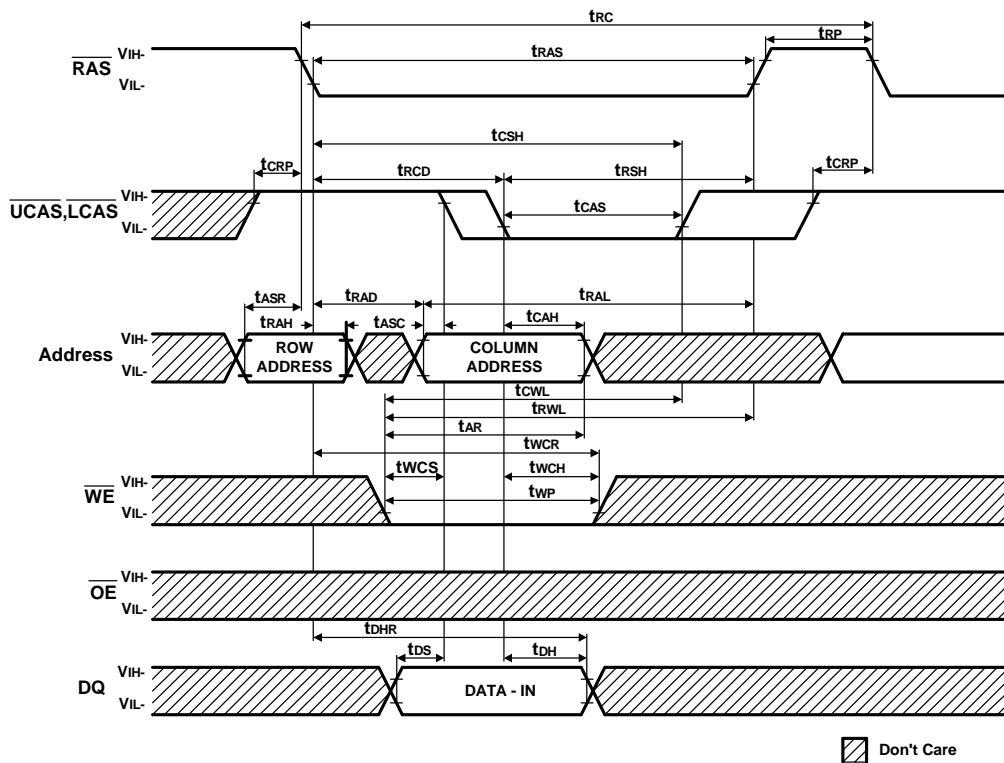
Parameter	Symbol	35		40		50		60		Unit	Notes
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Read or Write Cycle Time	t_{RC}	65		70		85		104		ns	
Read Modify Write Cycle Time	t_{RWC}	86		91		106		133		ns	
RAS Precharge Time	t_{RP}	25		25		30		40		ns	
RAS Pulse Width	t_{RAS}	35	100K	40	100K	50	100K	60	100k	ns	
Access Time from RAS	t_{RAC}		35		40		50		60	ns	1,2,3
Access Time from CAS	t_{CAC}		11		12		14		15	ns	1,5,10
Access Time from Column Address	t_{AA}		18		20		25		30	ns	1,5,6
CAS to Output Low-Z	t_{CLZ}	0		0		0		0		ns	
CAS to Output High-Z	t_{CEZ}	3	8	3	8	3	8	3	10	ns	
RAS Hold Time	t_{RSH}	12		12		14		13		ns	
RAS Hold Time Referenced to $\overline{\text{OE}}$	t_{ROH}	8		8		9		10		ns	
CAS Hold Time	t_{CSH}	30		34		45		40		ns	
CAS Pulse Width	t_{CAS}	6	10k	6	10k	8	10k	12	10k	ns	
RAS to CAS Delay Time	t_{RCD}	17	24	18	28	19	37	18	45	ns	
RAS to Column Address Delay Time	t_{RAD}	12	17	13	20	14	25	13	30	ns	7
CAS to RAS Precharge Time	t_{CRP}	5		5		5		5		ns	
Row Address Set-Up Time	t_{ASR}	0		0		0		0		ns	
Row Address Hold Time	t_{RAH}	7		8		9		10		ns	
Column Address Set-Up Time	t_{ASC}	0		0		0		0		ns	
Column Address Hold Time	t_{CAH}	6		6		7		10		ns	
Column Address to RAS Lead Time	t_{RAL}	18		20		25		30		ns	
Column Address Hold Time Referenced to RAS	t_{AR}	30		34		44		55		ns	
Read Command Set-Up Time	t_{RCS}	0		0		0		0		ns	
Read Command Hold Time Referenced to $\overline{\text{CAS}}$	t_{RCH}	0		0		0		0		ns	4
Read Command Hold Time Referenced to RAS	t_{RRH}	0		0		0		0		ns	4
Write Command Set-Up Time	t_{WCS}	0		0		0		0		ns	8,9
Write Command Hold Time	t_{WCH}	6		6		6		10		ns	
Write Command Pulse Width	t_{WP}	6		6		6		10		ns	
Write Command to RAS Lead Time	t_{RWL}	11		12		13		13		ns	
Write Command to CAS Lead Time	t_{CWL}	11		12		13		13		ns	

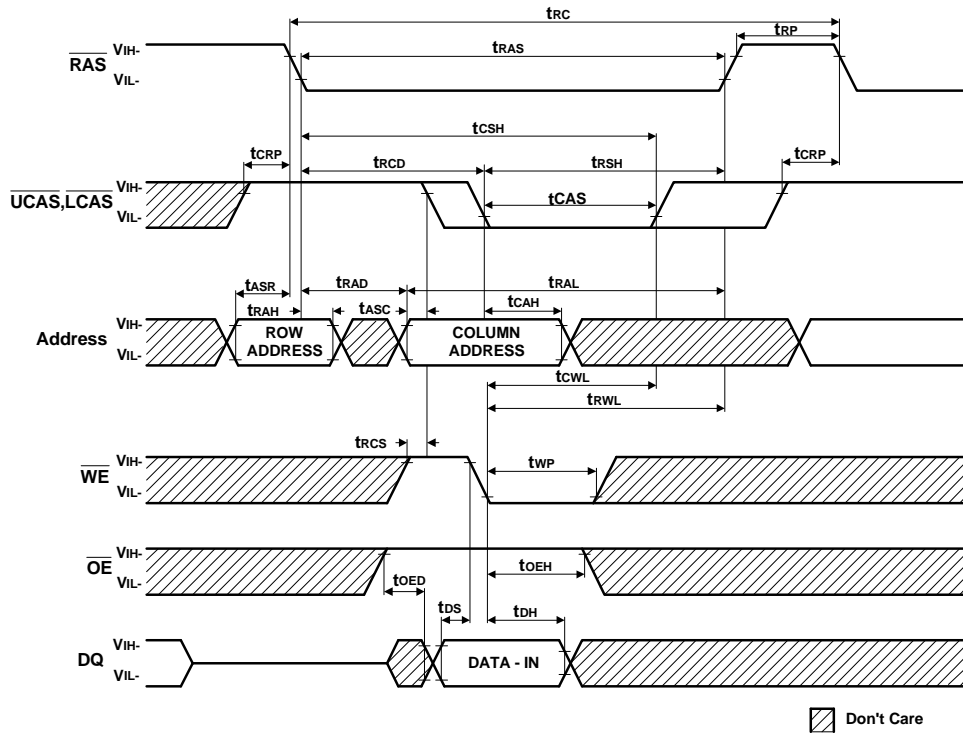
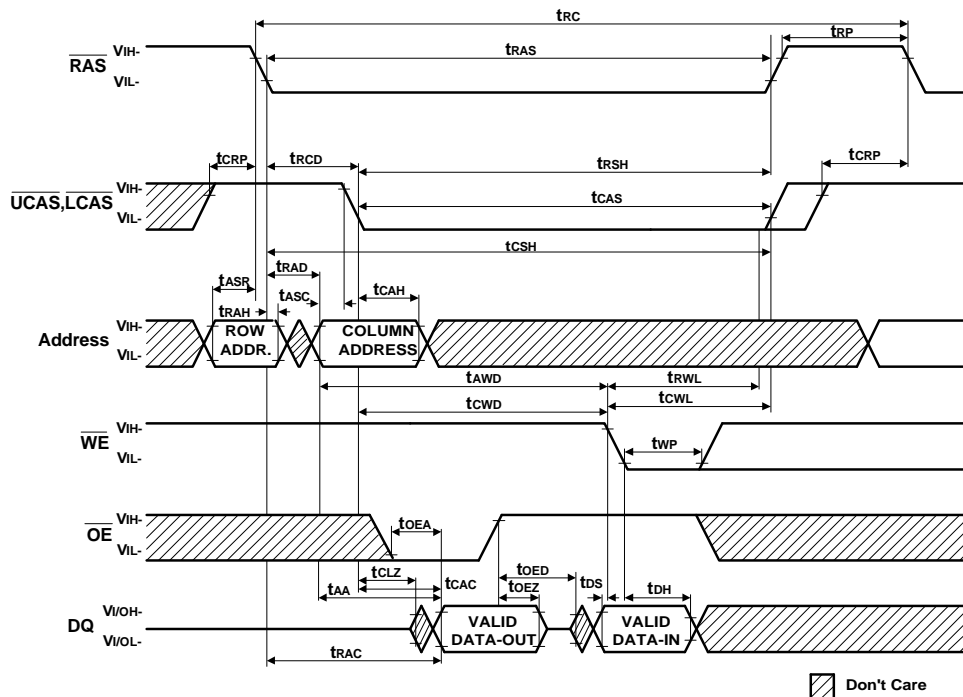
AC Characteristics

Parameter	Symbol	35		40		50		60		Unit	Notes
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Data Set-Up Time	t _{DS}	0		0		0		0		ns	
Data Hold Time	t _{DH}	7		7		8		10		ns	
Data Hold Time Referenced to $\overline{\text{RAS}}$	t _{DHR}	31		36		46		55		ns	
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay Time	t _{RWD}	49		54		64		79		ns	
$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ Delay Time	t _{CWD}	23		24		25		32		ns	
Column Address to $\overline{\text{WE}}$ Delay Time	t _{AWD}	30		32		37		47		ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Precharge Time	t _{RPC}	0		0		0		0		ns	
Access Time from $\overline{\text{CAS}}$ Precharge	t _{CPA}		20		22		30		32	ns	
EDO Page Mode Cycle Time	t _{PC}	13		15		20		25		ns	
EDO Page Mode Read-Modify-Write Cycle Time	t _{PRWC}	47		50		59		63		ns	
$\overline{\text{CAS}}$ Precharge Time (EDO Page Mode)	t _{CP}	5		5		8		15		ns	
$\overline{\text{RAS}}$ Pulse Width (EDO Page Mode Only)	t _{RASP}	35	100K	40	100K	50	100K	60	100k	ns	
Access Time from $\overline{\text{OE}}$	t _{OEA}		11		12		14		15	ns	
$\overline{\text{OE}}$ to Data Delay Time	t _{OED}	8		8		8		13		ns	
$\overline{\text{OE}}$ to Output High-Z	t _{OEZ}	3	8	3	8	3	8	3	8	ns	
$\overline{\text{OE}}$ Command Hold Time	t _{OEH}	6		7		7		0		ns	
Data Output Hold after $\overline{\text{CAS}}$ low	t _{DOH}	3		3		5		5		ns	
$\overline{\text{RAS}}$ to Output High-Z	t _{REZ}	3	8	3	8	3	8	3	8	ns	
$\overline{\text{WE}}$ to Output High-Z	t _{WEZ}	3	10	3	10	3	12	3	12	ns	
$\overline{\text{OE}}$ to $\overline{\text{CAS}}$ Hold Time	t _{OCH}	8		8		8		5		ns	
$\overline{\text{CAS}}$ Hold Time to $\overline{\text{OE}}$	t _{CHO}	8		8		8		5		ns	
$\overline{\text{OE}}$ Precharge Time	t _{OEP}	8		8		8		5		ns	
$\overline{\text{CAS}}$ Set-Up Time for $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Cycle	t _{CSR}	10		10		10		10		ns	
$\overline{\text{CAS}}$ Hold Time for $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Cycle	t _{CHR}	8		8		10		10		ns	
Transition Time	t _T	1.5	50	1.5	50	2	50	2	50	ns	
Refresh Period	t _{REF}		16		16		16		16	ms	
$\overline{\text{RAS}}$ pulse width ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Self refresh)	t _{RASS}	100		100		100		100		μs	
$\overline{\text{RAS}}$ precharge time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Self refresh)	t _{RPS}	60		70		90		110		ns	
$\overline{\text{CAS}}$ precharge time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Self refresh)	t _{CHS}	-50		-50		-50		-50		ns	

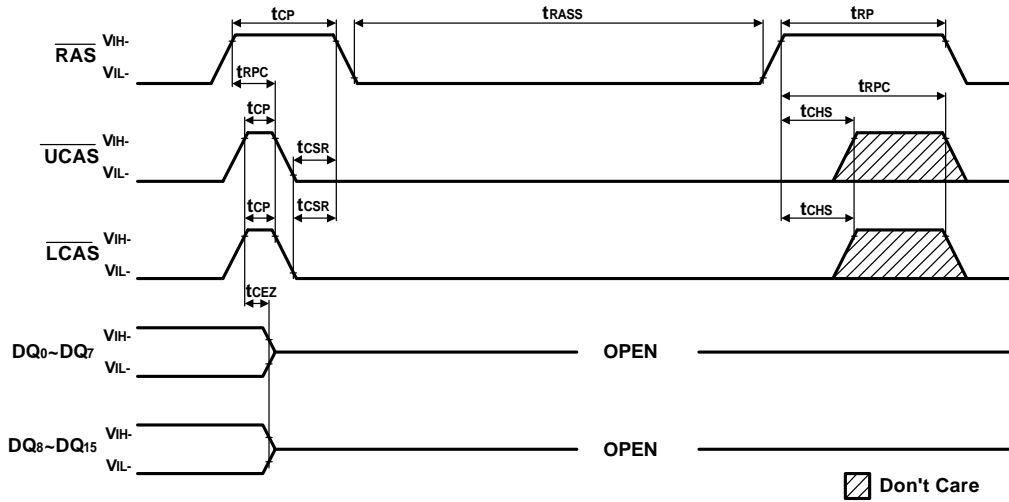
Notes:

1. Measure with a load equivalent to one TTL inputs and 50 pF.
2. Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}}(\text{max.})$. If t_{RCD} is greater than $t_{\text{RCD}}(\text{max.})$, access time will be t_{AA} dominant.
3. Assumes that $t_{\text{RAD}} \leq t_{\text{RAD}}(\text{max.})$. If t_{RAD} is greater than $t_{\text{RCD}}(\text{max.})$, access time will be controlled by t_{CAC} .
4. Either t_{RRH} or t_{RCH} must be satisfied for a Read Cycle.
5. Access time is determined by the longest of t_{CAA} , t_{CAC} and t_{CPA} .
6. Assumes that $t_{\text{RAD}} \geq t_{\text{RAD}}(\text{max.})$.
7. Operation within the $t_{\text{RAD}}(\text{max.})$ limit ensures that $t_{\text{RAC}}(\text{max.})$ can be met. $t_{\text{RAD}}(\text{max.})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{\text{RAD}}(\text{max.})$ limit, the access time is controlled by t_{CAA} and t_{CAC} .
8. t_{WCS} , t_{RWD} , t_{AWD} and t_{CWD} are not restrictive operating parameters.
9. $t_{\text{WCS}}(\text{min.})$ must be satisfied in an Early Write Cycle.
10. t_{DS} and t_{DH} are referenced to the latter occurrence of $\overline{\text{CAS}}$ of $\overline{\text{WE}}$.
11. t_{T} is measured between $V_{\text{IH}}(\text{min.})$ and $V_{\text{IL}}(\text{max.})$. AC-measurements assume $t_{\text{T}} = 1.5 \text{ ns}$.

Read CYCLE Note : $D_{IN} = OPEN$

Early Write Cycle NOTE : $D_{OUT} = OPEN$


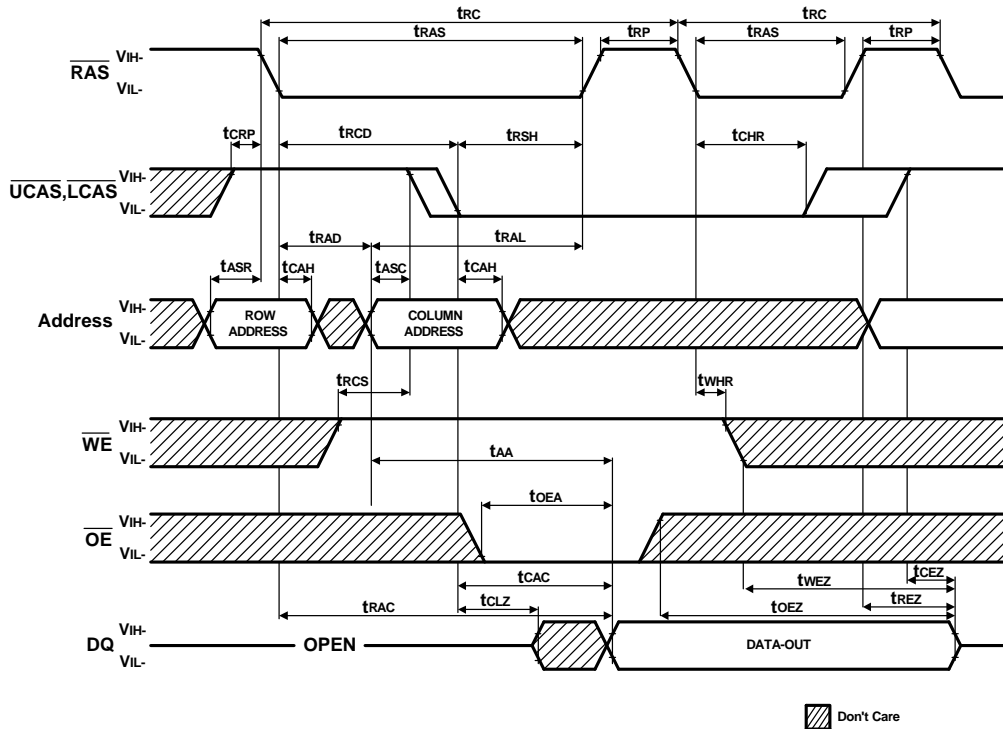
OE Controlled Write Cycle NOTE : D_{OUT} = OPEN

Read - Modify - Write Cycle


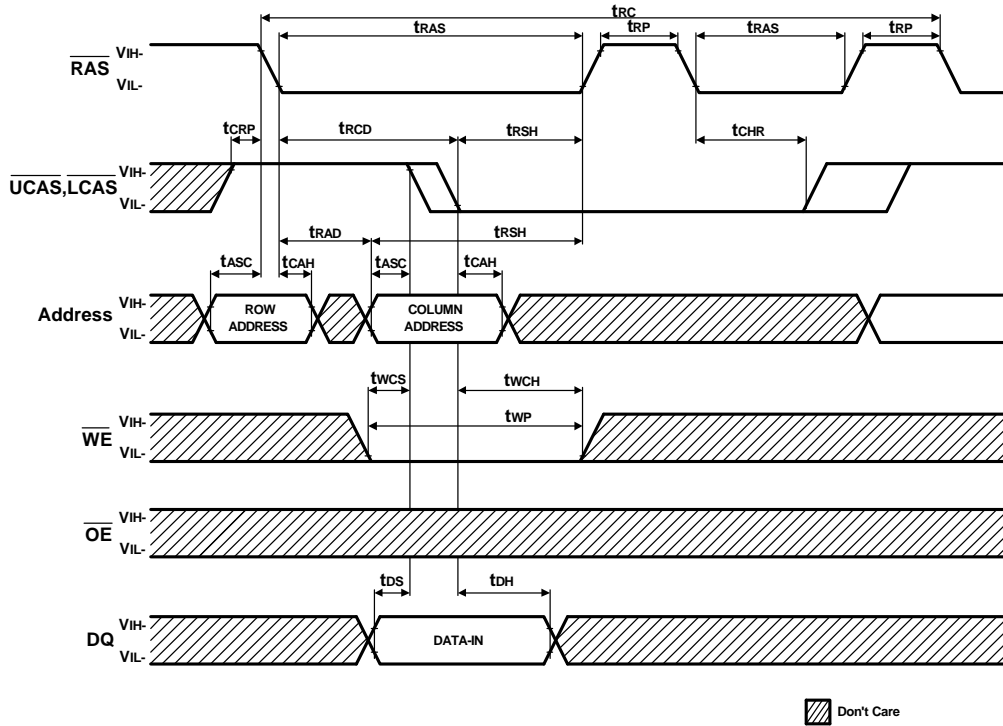
CAS - Before - RAS Self Refresh Cycle



NOTE : \overline{WE} , \overline{OE} , Address = Don't care.

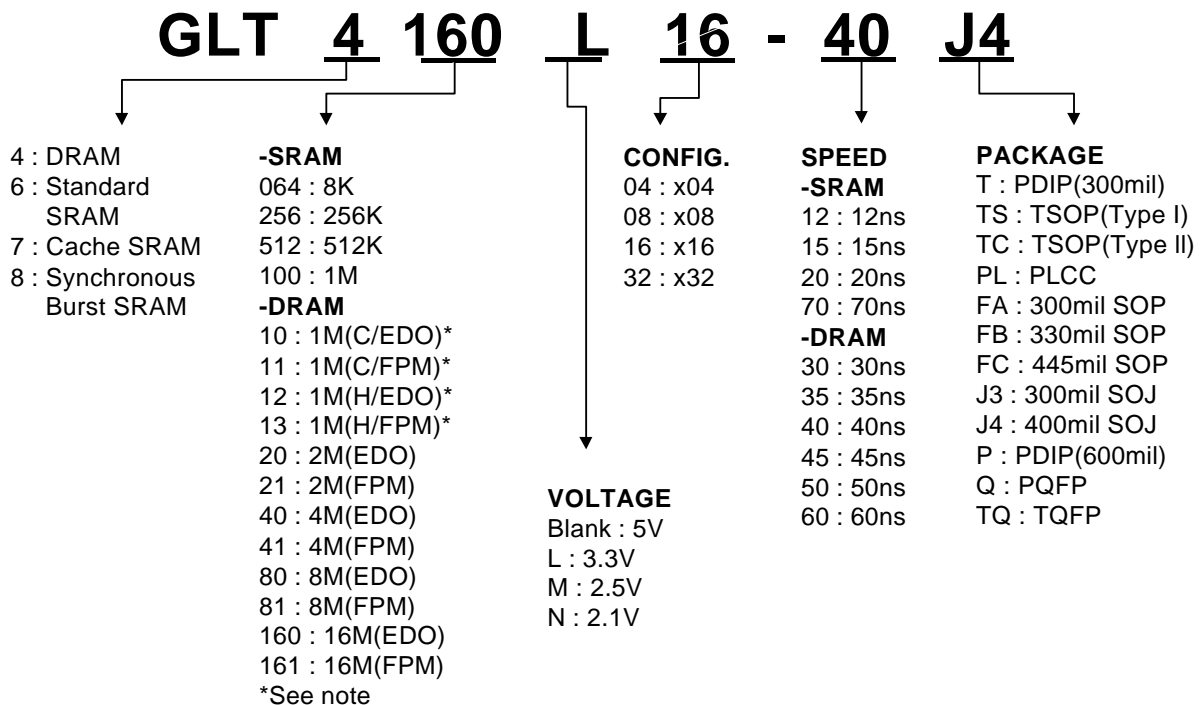
Hidden Refresh Cycle (Read)



Hidden Refresh Cycle (Write) NOTE : D_{OUT} = OPEN


Ordering Information

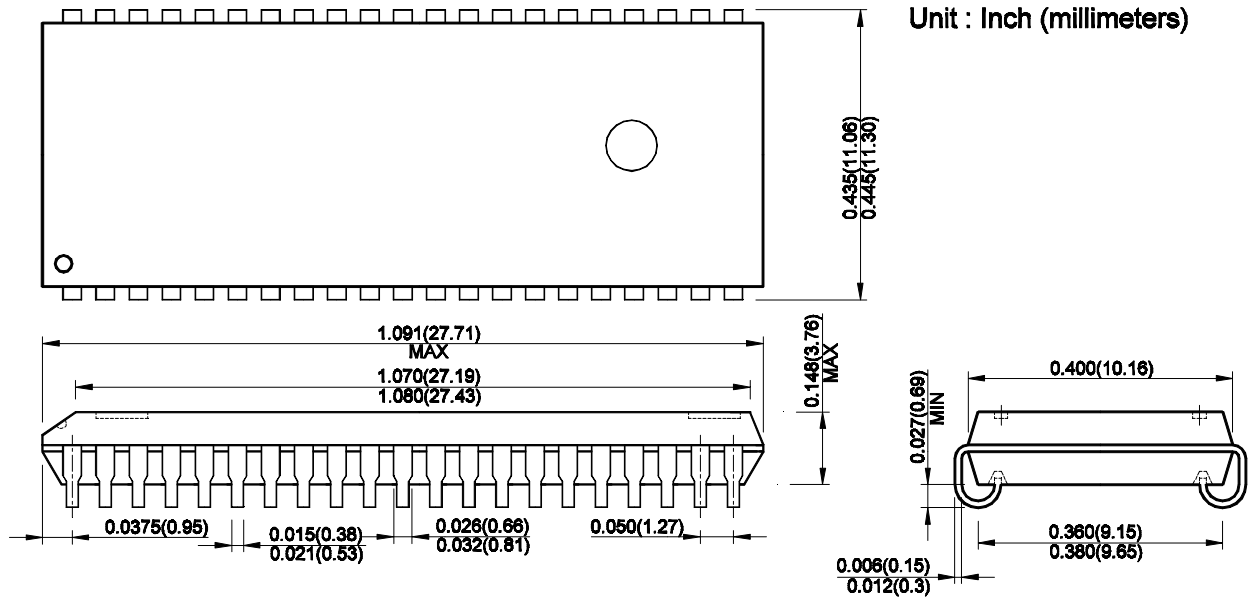
Part Number	SPEED	POWER	FEATURE	PACKAGE
GLT4160L16-35J4	35ns	Normal	EDO	42L 400mil SOJ
GLT4160L16-40J4	40ns	Normal	EDO	42L 400mil SOJ
GLT4160L16-50J4	50ns	Normal	EDO	42L 400mil SOJ
GLT4160L16-60J4	60ns	Normal	EDO	42L 400mil SOJ
GLT4160L16-35TC	35ns	Normal	EDO	44/50L 400mil TSOPII
GLT4160L16-40TC	40ns	Normal	EDO	44/50L 400mil TSOPII
GLT4160L16-50TC	50ns	Normal	EDO	44/50L 400mil TSOPII
GLT4160L16-60TC	60ns	Normal	EDO	44/50L 400mil TSOPII

Parts Numbers (Top Mark) Definition :


Note : C→CDROM , H→HDD.

Example :

1. GLT710008-15T 1Mbit(128Kx8)15ns 5V SRAM PDIP(300mil)Package type.
2. GLT44016-40J4 4Mbit(256Kx16)40ns 5V DRAM SOJ(400mil)Package type.

Package Information
40/42L 400MIL SOJ

44/50L TSOPII 400MIL
